




PCN Number:	20200304005.1			PCN Date:	Mar 5, 2020									
Title:	Qualification of Carsem Suzhou an additional Assembly site for Select Devices													
Customer Contact:	PCN Manager	Dept:	Quality Services											
Proposed 1st Ship Date:	June 5, 2020		Estimated Sample Availability:	Date provided at sample request										
Change Type:														
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site									
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material									
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process									
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site									
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials									
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process									
PCN Details														
Description of Change:														
<p>Texas Instruments is pleased to announce the qualification Carsem Suzhou as an additional assembly site for the list of devices below. Current assembly site and Material differences are as follows:</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th></th> <th>CDAT</th> <th>Carsem</th> </tr> </thead> <tbody> <tr> <td>Mount Compound</td> <td>4207123</td> <td>SID#443156</td> </tr> <tr> <td>Mold Compound</td> <td>4222198</td> <td>SID#441086</td> </tr> </tbody> </table>							CDAT	Carsem	Mount Compound	4207123	SID#443156	Mold Compound	4222198	SID#441086
	CDAT	Carsem												
Mount Compound	4207123	SID#443156												
Mold Compound	4222198	SID#441086												
Reason for Change:														
Continuity of Supply														
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):														
None														
Anticipated impact on Material Declaration														
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp											
Changes to product identification resulting from this PCN:														
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City											
TI Chengdu	CDA	CHN	Chengdu											
Carsem	CSZ	CHN	Jiangsu											
Sample product shipping label (not actual product label)														

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

MADE IN: Malaysia
2DC: 20:
MSL '2 /260C/1 YEAR SEAL DT
MSL 1 /235C/UNLIM 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)T0:1750

Product Affected:

BQ25710RSNR	BQ25713BRSNR	BQ25713RSNR	BQ25713RSNT
BQ25710RSNT	BQ25713BRSNT		



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Selective Disclosure

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	QBS Product Reference: BQ25700ARSNR	QBS Product Reference: BQ25710RSNR	QBS Process Reference: TPS51217DSC	QBS Package Reference: TLC5951RTA
AC	Autoclave 121C	96 Hours	-	-	6/462/0	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass
ELFR	Early Life Failure Rate, 85C	48 Hours	-	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-
HAST	Biased HAST, 110C/85%RH	264 Hours	-	-	-	3/231/0
HBM	ESD - HBM	2000 V	1/3/0	-	3/9/0	1/3/0
HBM	ESD - HBM Relay Based (Mk2) Disposition	Split A1/1000V	-	-	-	-
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	3/9/0	1/3/0
HTOL	Life Test, 125C	1000 Hours	1/77/0	-	-	1/77/0
HTOL	Life Test, 135C	635 Hours	-	-	3/231/0	-
HTOL	Life Test, 70C	1000 Hours	-	-	-	-
HTOL	Life Test, 70C	1052 Hours	-	-	-	-
HTOL	Life Test, 70C	452 Hours	-	-	-	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/231/0	1/50/0
LU	Latch-up	(per JESD78)	1/12/0	1/6/0	3/18/0	1/6/0
SD	Solderability	Pb Free	-	-	-	3/15/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	-	2/231/0
WBP	Bond Strength	Wires	-	-	-	3/108/0
WBS	Ball Bond Shear	Wires	-	-	-	3/108/0

- QBS: Qual By Similarity
- Qual Devices qualified at LEVEL2-260CG: BQ25710RSN
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

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